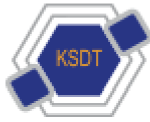

**Dr. Ye Feng**

Senior Technical Director, Intel, U.S.

Ye Feng is responsible for reducing process variability and improve yields for Intel's advanced nodes. He leverages advanced analytics for process control, recipe optimization, and virtual metrology. Dr. Feng joined Intel in 2022 after 21 years with Lam Research and Onto Innovations. Previously, he was a senior technical director at Lam Research, pioneering ML-based in situ endpoint solutions for etch process control. At Nanometrics (now Onto Innovations), he introduced 3D scatterometry solution to Intel for FinFET metrology, now an industry process of record. Dr. Feng has lead innovations in algorithms, sensor and metrology applications, simulations, and process control. He holds a Ph.D. in Physics from Iowa State University and an executive MBA from the University of Oregon. He has sixteen patents published or pending and serves on the program committee of the FCMN conference.